

AMENDMENTS TO THE CLAIMS

1. **(Currently Amended)** A relay block free from melt wrinkles and comprising a resin composition which contains a polyamide, a polyphenylene ether, a block copolymer comprising at least one polymer block mainly composed of an aromatic vinyl compound and at least one polymer block mainly composed of a conjugated diene compound, at least one transition metal selected from the group consisting of copper, nickel and cobalt and at least one halogen selected from the group consisting of chlorine, iodine and bromine, and which has a melt volume rate (MVR) [measured at a test temperature of 280°C under a load of 5.0 kg in accordance with method B of ISO1133: 1997] of not less than 60 cm³/10 min., ~~and~~ a dimensional change after water absorption [change of dimension in the flow direction after being subjected to water absorption treatment at a temperature of 90°C and a humidity of 95% for 72 hours as compared with the dimension before subjecting to water absorption treatment (measured using a plate of type D2 of 2 mm thick specified in ISO294-3: 1996 which is molded at a melting temperature of 290°C and a mold temperature of 90°C under the molding conditions specified in ISO15103-2: 1997)] of not more than 1.0% and a reduced viscosity of polyphenylene ether in the resin composition of 0.40 - 0.45 dl/g.

2. (Original) A relay block according to claim 1 which has, at a periphery of a slit of a bus bar inserting portion constituting a part of the relay block, parallel planes having the same shape which form the slit and are disposed opposite to each other, and has a degree of deformation between the parallel planes of not more than 1% (a value obtained by dividing the difference between the maximum and the minimum values of a distance in the horizontal direction between the parallel planes at the uppermost part of the parallel planes by a unit length of the parallel planes in the horizontal direction).

3. (Original) A relay block according to claim 1, wherein the ratio of wall thickness of the relay block (the ratio of thickness of the maximum wall thickness portion to the thickness of the minimum wall thickness portion) satisfies a range of not less than 10.

4. (Original) A relay block according to claim 1, wherein the weight of molded product per one gate in molding of the relay block is not less than 20 g.

5. (Original) A relay block according to claim 1, wherein the resin composition constituting the relay block has a deflection temperature under load [measured in accordance with ASTM D648-95 using a test piece of about 6.4 mm in width under a stress of 1.82 MPa] of not lower than 105°C.

6. (Original) A relay block according to claim 1, wherein the resin composition constituting the relay block has a shrinkage anisotropy (the ratio of molding shrinkage in the direction perpendicular to the flow direction to the molding shrinkage in the direction parallel to the flow direction measured in accordance with ISO294-4: 1997 using a plate of type D2 of 2 mm thick specified in ISO294-3: 1996 molded at a melting temperature of 290°C and a mold temperature of 90°C under the molding conditions specified in ISO15103-2: 1997) of 0.70-1.30.

7. (Original) A relay block according to claim 1, wherein the resin composition further contains an oil.

8. (Original) A relay block according to claim 1, wherein the content of polyamide in the resin composition is 55-70% by weight.

9. (Original) A relay block according to claim 1, wherein polyamide 6,6 is contained in an amount of not less than 70% by weight of the total amount of the polyamide in the resin composition.

10. (Original) A relay block according to claim 8 or 9, wherein the polyamide in the resin composition is a mixture of polyamide 6,6 and polyamide 6.

11. **(Currently Amended)** A relay block comprising a resin composition which contains a polyamide, a polyphenylene ether, a block copolymer comprising at least one polymer block mainly composed of an aromatic vinyl compound and at least one polymer block mainly composed of a conjugated diene compound, at least one transition metal selected from the group consisting of copper, nickel and cobalt and at least one halogen selected from the group consisting of chlorine, iodine and bromine and further contains a flame retardant containing substantially no halogen in an amount effective for flame retardation of the resin composition, a reduced viscosity of polyphenylene ether in the resin composition being 0.40-0.45 dl/g.

12. (Original) A relay block according to claim 11, wherein the flame retardant containing substantially no halogen comprises two or more flame retardants.

13. (Original) A relay block according to claim 11, wherein the flame retardant containing substantially no halogen is a mixture of a flame retardant effective for flame retardation of polyamide and a flame retardant effective for flame retardation of polyphenylene ether.

14. (Original) A relay block according to claim 11, wherein the resin composition has a melt volume rate (MVR) [measured at a test temperature of 280°C and under a load of 5.0 kg in accordance with method B of ISO1133: 1997] of not less than 60 cm³/10 min. and a dimensional change after water absorption [change of dimension in the flow direction after subjecting to water absorption treatment at a temperature of 90°C and a humidity of 95% for 72 hours as compared with the dimension before subjecting to water absorption treatment (measured using a plate of type D2 of 2 mm thick specified in ISO294-3: 1996 which is molded at a melting temperature of 290°C and a mold temperature of 90°C under the molding conditions specified in ISO15103-2: 1997)] of not more than 1.0%.

15. (Original) A relay block according to claim 11, wherein the resin composition has a deflection temperature under load [measured in accordance with ASTM D648-95 using a test piece of about 6.4 mm in width under a load of 1820 kPa] of not lower than 105°C.

16. (Currently Amended) A resin composition which contains a polyamide, a polyphenylene ether, a block copolymer comprising at least one polymer block mainly composed of an aromatic vinyl compound and at least one polymer block mainly composed of a conjugated diene compound, at least one transition metal selected from the group consisting of copper, nickel and cobalt, at least one halogen selected from the group consisting of chlorine, iodine and bromine and an oil, and which has a melt volume rate (MVR) [measured at a test temperature of 280°C and under a load of 5.0 kg in accordance with method B of ISO1133: 1997] of not less than 60 cm³/10 min., and a dimensional change after water absorption [change of dimension of a molded piece in the flow direction after being subjected to water absorption treatment at a temperature of 90°C and a humidity of 95% for 72 hours as compared with the dimension just after molding (measured using as the molded piece a plate of type D2 of 2 mm thick specified in

ISO294-3: 1996 which is molded at a melting temperature of 290°C and a mold temperature of 90°C under the molding conditions specified in ISO15103-2: 1997)] of not more than 1.0% and a reduced viscosity of polyphenylene ether in the resin composition of 0.40-0.45 dl/g.

17. (Original) A resin composition according to claim 16, wherein the oil is mainly composed of paraffin.

18. (Original) A resin composition according to claim 16, wherein the polyamide has a viscosity number of 100-130 ml/g measured in 96% sulfuric acid in accordance with ISO307: 1994.

19. (Original) A resin composition according to claim 16 wherein polyamide 6,6 is contained in an amount of not less than 70% by weight of the total amount of the polyamide.

20. (Original) A resin composition according to claim 18 or 19, wherein the polyamide is a mixture of polyamide 6,6 and polyamide 6.

21. (Previously Presented) A resin composition according to claim 16 wherein a content of the transition metal is 10-200 ppm and a content of the halogen is 500-1500 ppm.

22. (Original) A resin composition according to claim 16, wherein a transition metal and/or a halogen are previously mixed with the polyamide and then the polyamide is blended in the resin composition.

23. (Original) A resin composition according to claim 22, wherein the transition metal and/or the halogen are previously added to polyamide 6 at a high concentration (500 ppm or higher for the transition metal and 10000 ppm or higher for the halogen) and then the polyamide 6 is blended in the resin composition.

24. (Original) A resin composition according to claim 16 which contains a flame retardant containing substantially no halogen.

25. (Original) A resin composition according to claim 24, wherein the flame retardant containing substantially no halogen is a mixture of two or more flame retardants.

26. (Original) A resin composition according to claim 24 or 25, wherein the flame retardant containing substantially no halogen is a mixture of a flame retardant effective for flame retardation of polyamide and a flame retardant effective for flame retardation of polyphenylene ether.

27. (Cancelled)